

DZ3X068D

Silicon epitaxial planar type

For surge absorption circuit

■ Features

- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 02

■ Packaging

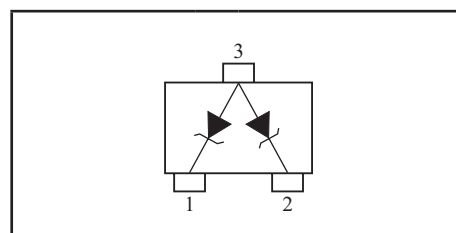
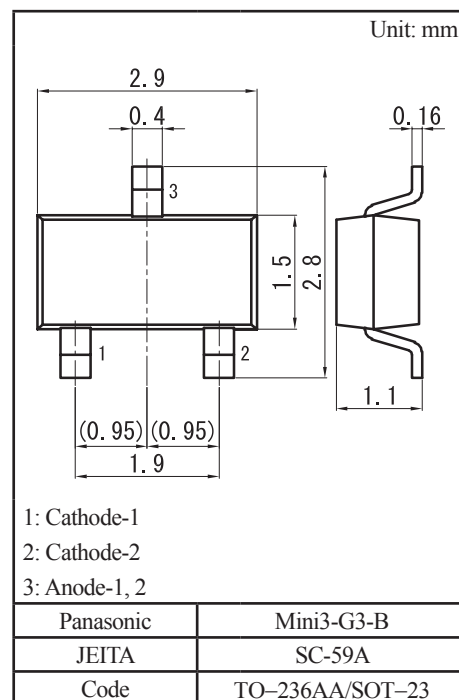
DZ3X068D0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Total power dissipation ^{*1}	P_T	200	mW
Electrostatic discharge ^{*2}	ESD	± 10	kV
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: Mounted on glass epoxy print board. (45 mm × 45 mm × 1 mm) (2 Diode total)
Solder in (1.0 mm × 1.0 mm)

*2: Test method:IEC61000-4-2 (C = 150 pF, R = 330 Ω , Contact discharge:10 times)



■ Common Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

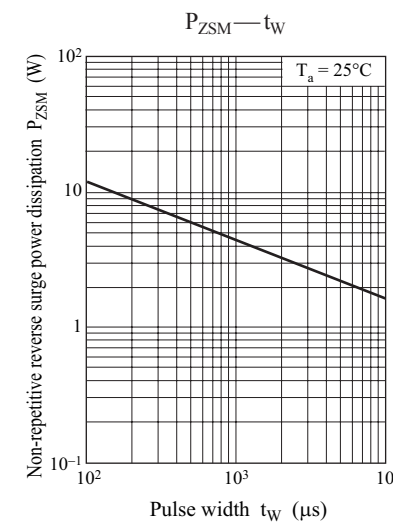
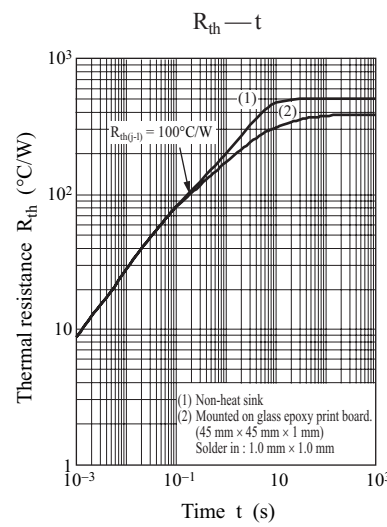
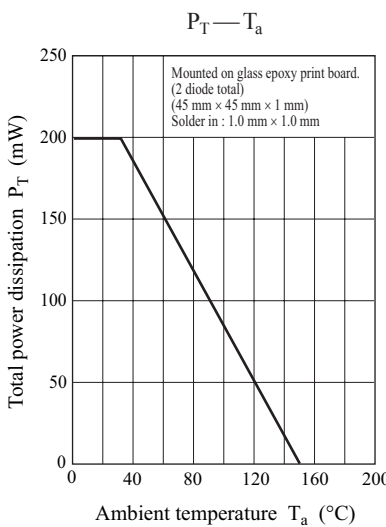
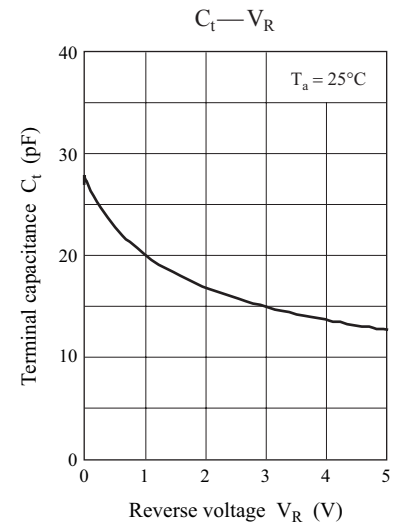
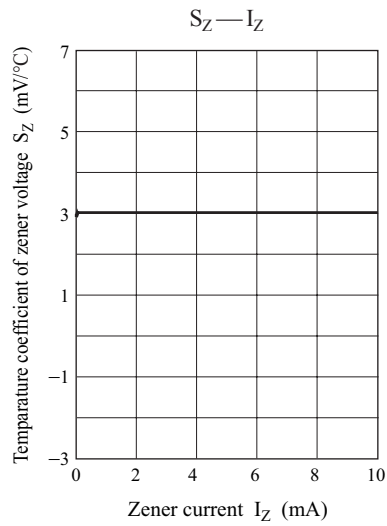
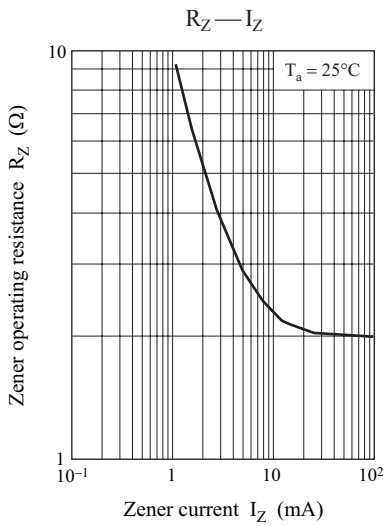
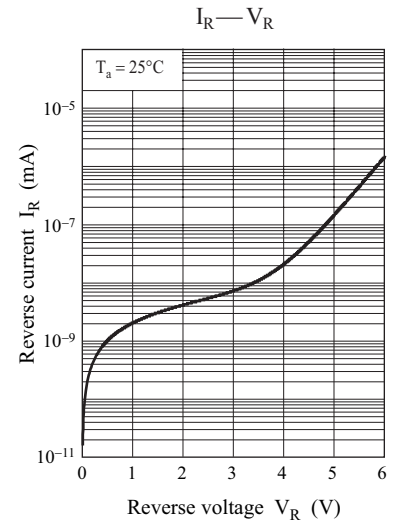
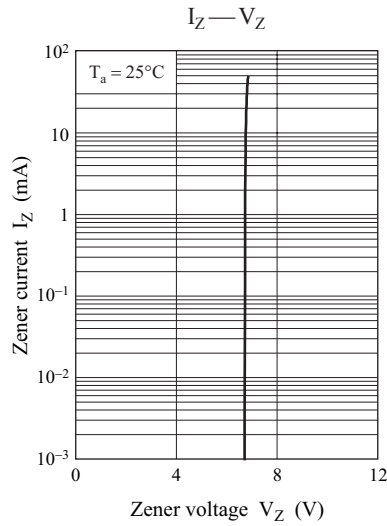
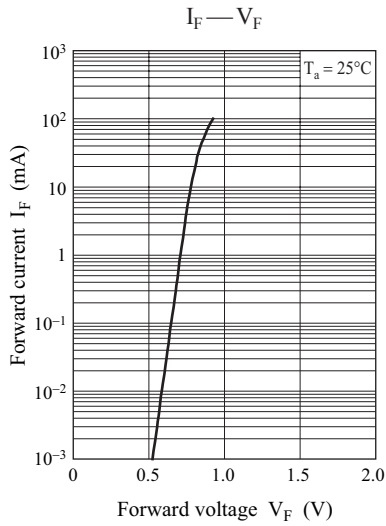
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10 \text{ mA}$			1.0	V
Zener voltage ^{*1,2}	V_Z	$I_Z = 5 \text{ mA}$	6.46		7.14	V
Zener operating resistance	R_Z	$I_Z = 5 \text{ mA}$			30	Ω
Zener rise operating resistance	R_{ZK}	$I_Z = 0.5 \text{ mA}$			60	Ω
Reverse current	I_R	$V_R = 4 \text{ V}$			0.1	μA
Temperature coefficient of zener voltage ^{*3}	S_Z	$I_Z = 5 \text{ mA}$		3.1		mV/ $^\circ\text{C}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to $V_Z (25^\circ\text{C})$

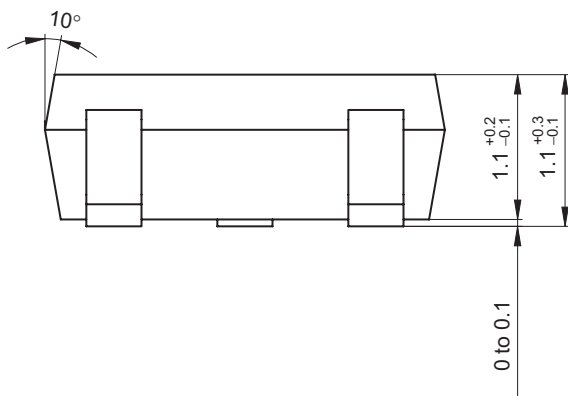
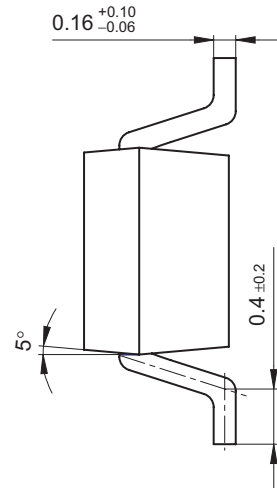
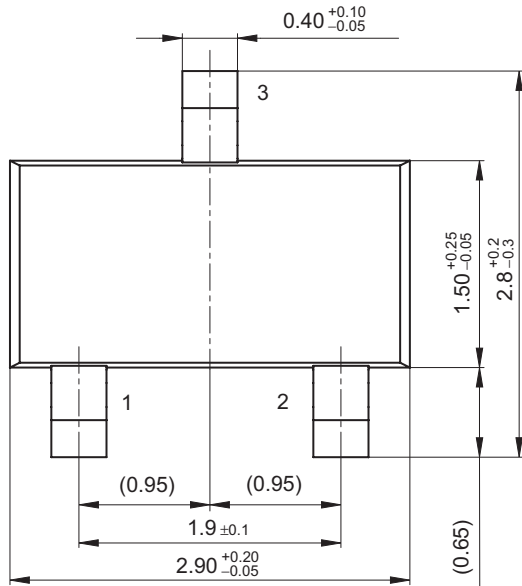
*2: V_Z guaranteed 20 ms after current flow.

*3: $T_j = 25^\circ\text{C}$ to 150°C

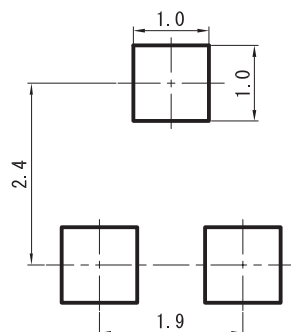


Mini3-G3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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